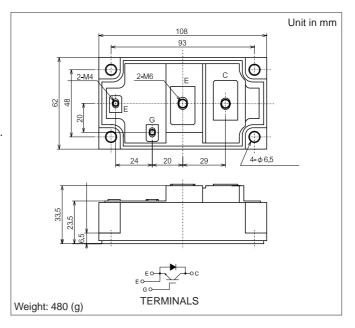
# MBN400GS12BW

Silicon N-channel IGBT

#### **OUTLINE DRAWING**

#### **FEATURES**

- \* High speed and low saturation voltage.
- \* low noise due to built-in free-wheeling diode ultra soft fast recovery diode(USFD).
- \* Isolated head sink (terminal to base).



ABSOLUTE MAXIMUM RATINGS (Tc=25°C)

| <br>Item                    |                  | Symbol          | Unit               | MBN400GS12BW          |  |  |
|-----------------------------|------------------|-----------------|--------------------|-----------------------|--|--|
| Collector Emitter Voltage   |                  | Vces            | V                  | 1,200                 |  |  |
| Gate Emitter Voltage        |                  | $V_{GES}$       | V                  | ±20                   |  |  |
| Collector Current           | DC               | Ic              | Α                  | 400                   |  |  |
|                             | 1ms              | I <sub>Cp</sub> | A                  | 800                   |  |  |
| Forward Current             | DC               | lF              | А                  | 400 (1)               |  |  |
|                             | 1ms              | I <sub>FM</sub> | A                  | 800                   |  |  |
| Collector Power Dissipation |                  | Pc              | W                  | 2,000                 |  |  |
| Junction Temperature        | Tj               | °C              | -40 ~ +150         |                       |  |  |
| Storage Temperature         | T <sub>stg</sub> | °C              | -40 ~ +125         |                       |  |  |
| Isolation Voltage           | V <sub>ISO</sub> | $V_{RMS}$       | 2,500(AC 1 minute) |                       |  |  |
| Screw Torque Ter            | minals           | -               | N.m                | 1.37(14)/2.94(30) (2) |  |  |
| Mo                          | unting           | -               | (kgf.cm)           | 2.94(30) (3)          |  |  |

Notes:(1)RMS Current of Diode 180Arms max.

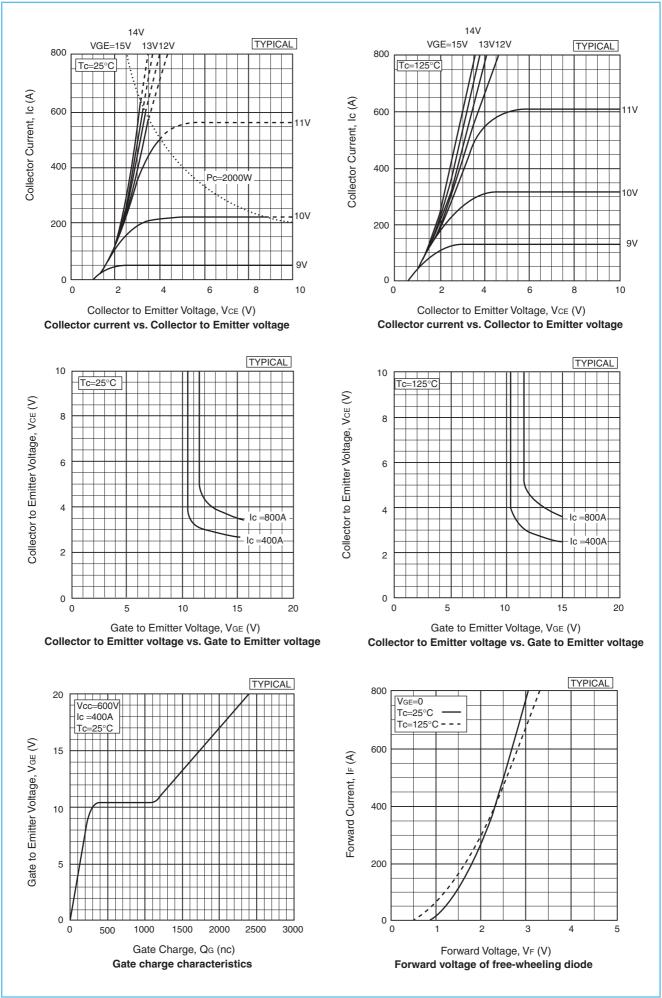
(2)Recommended Value 1.18/2.45N.m(12/25kgf.cm)

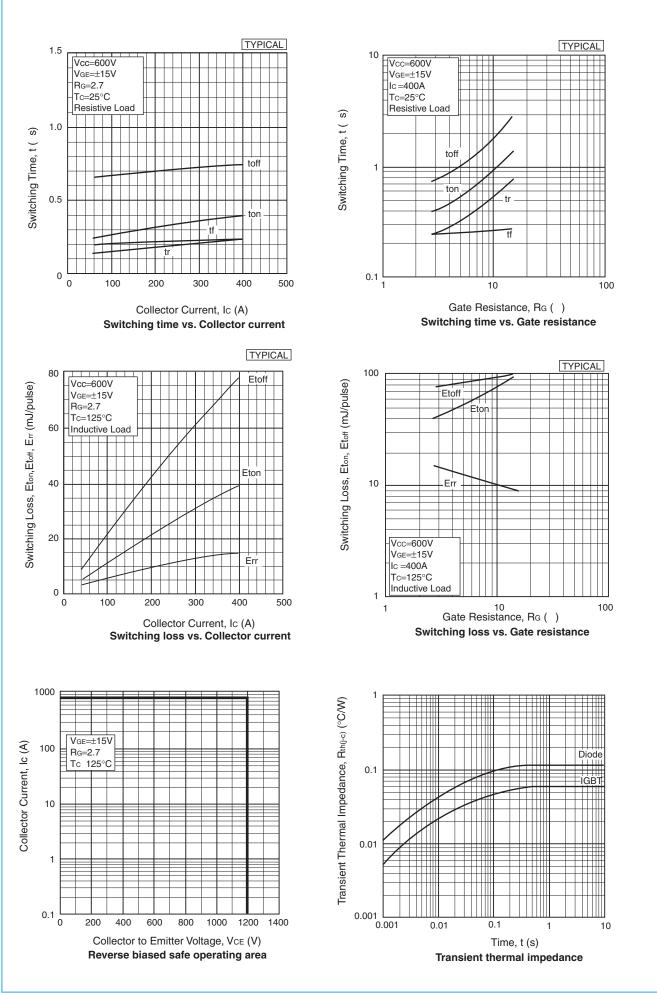
(3) Recommended Value 2.45N.m(25kgf.cm)

### CHARACTERISTICS (Tc=25°C)

| 0.11 to 10.11 (1.0 Lo 0)             |               |                      |          |      |        |      |                                                           |  |
|--------------------------------------|---------------|----------------------|----------|------|--------|------|-----------------------------------------------------------|--|
| Item                                 |               | Symbol               | Unit     | Min. | Тур.   | Max. | Test Conditions                                           |  |
| Collector Emitter Cut-Off Current    |               | I <sub>CES</sub>     | mA       | -    | -      | 1.0  | V <sub>CE</sub> =1,200V,V <sub>GE</sub> =0V               |  |
| Gate Emitter Leakage Current         |               | I <sub>GES</sub>     | nA       | -    | -      | ±500 | V <sub>GE</sub> =±20V,V <sub>CE</sub> =0V                 |  |
| Collector Emitter Saturation Voltage |               | V <sub>CE(sat)</sub> | V        | -    | 2.7    | 3.4  | I <sub>C</sub> =400A,V <sub>GE</sub> =15V                 |  |
| Gate Emitter Threshold Voltage       |               | V <sub>GE(TO)</sub>  | <b>V</b> | -    | -      | 10   | $V_{CE}=5V$ , $I_{C}=400mA$                               |  |
| Input Capacitance                    |               | Cies                 | pF       | -    | 37,000 | -    | V <sub>CE</sub> =10V,V <sub>GE</sub> =0V,f=1MHz           |  |
|                                      | Rise Time     | tr                   |          | -    | 0.25   | 0.5  | V <sub>CC</sub> =600V                                     |  |
| Switching Times                      | Turn On Time  | ton                  | μS       | -    | 0.4    | 0.7  | $R_L=1.5\Omega$                                           |  |
| Ü                                    | Fall Time     | t <sub>f</sub>       |          | -    | 0.25   | 0.35 | $R_G=2.7\Omega$ (4)                                       |  |
|                                      | Turn Off Time | t <sub>off</sub>     |          | -    | 0.75   | 1.1  | V <sub>GE</sub> =±15V                                     |  |
| Peak Forward Voltage Drop            |               | V <sub>FM</sub>      | V        | -    | -      | 3.5  | I <sub>F</sub> =400A,V <sub>GE</sub> =0V                  |  |
| Reverse Recovery Time                |               | trr                  | μS       | -    | -      | 0.4  | I <sub>F</sub> =400A,V <sub>GE</sub> =-10V, di/dt=400A/μs |  |
| Thermal Impedance IGBT               |               | Rth(j-c)             | °C/W     | -    | -      | 0.06 | Junction to case                                          |  |
|                                      | FWD           | Rth(j-c)             |          | -    | -      | 0.12 |                                                           |  |

Notes:(4) R<sub>G</sub> value is the test condition's value for decision of the switching times, not recommended value. Determine the suitable R<sub>G</sub> value after the measurement of switching waveforms (overshoot voltage,etc.)with appliance mounted.





## HITACHI POWER SEMICONDUCTORS

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